FAST PRODUCTS

DATA SHEET

74F373
Octal transparent latch (3-State)
74F374
Octal D flip-flop (3-State)

Product specification

1994 Dec 05

IC15 Data Handbook

Philips Semiconductors





Latch/flip-flop

74F373/74F374

74F373 Octal transparent latch (3-State) 74F374 Octal D-type flip-flop (3-State)

FEATURES

- 8-bit transparent latch 74F373
- 8-bit positive edge triggered register 74F374
- 3-State outputs glitch free during power-up and power-down
- Common 3-State output register
- Independent register and 3-State buffer operation
- SSOP Type II Package

DESCRIPTION

The 74F373 is an octal transparent latch coupled to eight 3-State output devices. The two sections of the device are controlled independently by enable (E) and output enable ($\overline{\text{OE}}$) control gates.

The data on the D inputs is transferred to the latch outputs when the enable (E) input is high. The latch remains transparent to the data input while E is high, and stores the data that is present one setup time before the high-to-low enable transition.

The 3-State output buffers are designed to drive heavily loaded 3-State buses, MOS memories, or MOS microprocessors.

The active low output enable (\overline{OE}) controls all eight 3-State buffers independent of the latch operation. When \overline{OE} is low, latched or transparent data appears at the output.

When $\overline{\text{OE}}$ is high, the outputs are in high impedance "off" state, which means they will neither drive nor load the bus.

The 74F374 is an 8-bit edge triggered register coupled to eight 3-State output buffers. The two sections of the device are controlled independently by clock (CP) and output enable (OE) control gates.

The register is fully edge triggered. The state of the D input, one setup time before the low-to-high clock transition is transferred to the corresponding flip-flop's Q output.

The 3-State output buffers are designed to drive heavily loaded 3-State buses, MOS memories, or MOS microprocessors.

The active low output enable (\overline{OE}) controls all eight 3-State buffers independent of the register operation. When \overline{OE} is low, the data in the register appears at the outputs. When \overline{OE} is high, the outputs are in high impedance "off" state, which means they will neither drive nor load the bus.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F373	4.5ns	35mA

TYPE	TYPICAL f _{max}	TYPICAL SUPPLY CURRENT (TOTAL)
74F374	165MHz	55mA

ORDERING INFORMATION

	ORDER CODE	
DESCRIPTION	COMMERCIAL RANGE	PKG DWG #
	$V_{CC} = 5V \pm 10\%, T_{amb} = 0^{\circ}C \text{ to } +70^{\circ}C$	
20-pin plastic DIP	N74F373N, N74F374N	SOT146-1
20-pin plastic SOL	N74F373D, N74F374D	SOT163-1
20-pin plastic SSOP type II	N74F373DB, N74374DB	SOT399-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

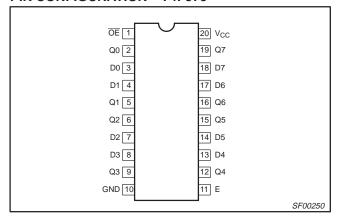
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0 - D7	Data inputs	1.0/1.0	20μA/0.6mA
E (74F373)	Enable input (active high)	1.0/1.0	20μA/0.6mA
ŌĒ	Output enable inputs (active low)	1.0/1.0	20μA/0.6mA
CP (74F374) Clock pulse input (active rising edge)		1.0/1.0	20μA/0.6mA
Q0 - Q7	3-State outputs	150/40	3.0mA/24mA

NOTE: One (1.0) FAST unit load is defined as: 20μA in the high state and 0.6mA in the low state.

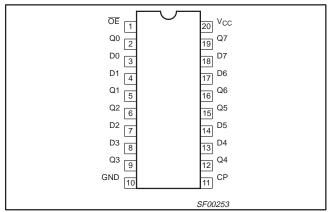
Latch/flip-flop

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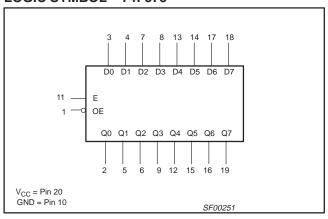
PIN CONFIGURATION - 74F373



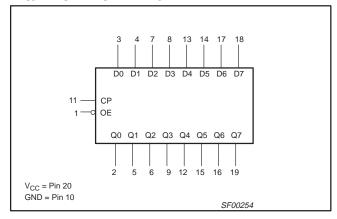
PIN CONFIGURATION - 74F374



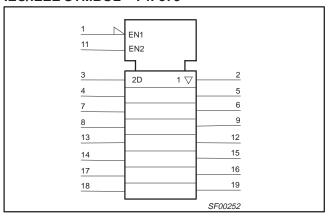
LOGIC SYMBOL - 74F373



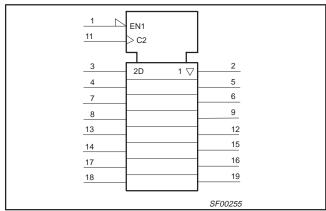
IEC/IEE SYMBOL - 74F374



IEC/IEEE SYMBOL - 74F373



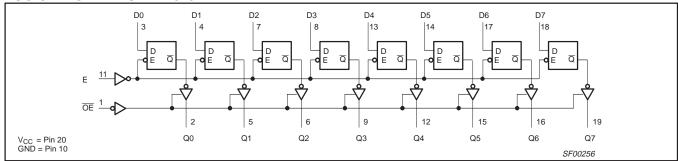
IEC/IEEE SYMBOL - 74F374



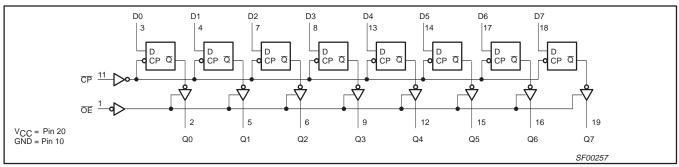
Latch/flip-flop

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LOGIC DIAGRAM FOR 74F373



LOGIC DIAGRAM FOR 74F374



FUNCTION TABLE FOR 74F373

	INPUTS		INTERNAL	OUTPUTS	OPERATING MODE
ŌĒ	E	Dn	REGISTER	Q0 - Q7	OPERATING MODE
L	Н	L	L	L	Enable and read register
L	Н	Н	Н	Н	Enable and read register
L	\downarrow	I	L	L	Latch and read register
L	\downarrow	h	Н	Н	Laterrand read register
L	L	Х	NC	NC	Hold
Н	Ĺ	Х	NC	Z	Disable outputs
Н	Н	Dn	Dn	Z	Disable outputs

NOTES:

H = High-voltage level

High state must be present one setup time before the high-to-low enable transition h

L Low-voltage level

Low state must be present one setup time before the high-to-low enable transition

NC= No change X = Z = ↓ = Don't care

High impedance "off" state

High-to-low enable transition

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FUNCTION TABLE FOR 74F374

	INPUTS		INTERNAL	OUTPUTS	OPERATING MODE
ŌĒ	СР	Dn	REGISTER	Q0 - Q7	OFERATING MODE
L	1	-	L	L	Load and read register
L	1	h	Н	Н	Loau and read register
L	1	Х	NC	NC	Hold
Н	1	Х	NC	Z	Disable cutnute
Н	1	Dn	Dn	Z	Disable outputs

NOTES:

H = High-voltage level

High state must be present one setup time before the low-to-high clock transition

L = Low-voltage level

= Low state must be present one setup time before the low-to-high clock transition

NC= No change

X = Don't care

Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in high output state	-0.5 to V _{CC}	V
I _{OUT}	Current applied to output in low output state	48	mA
T _{amb}	Operating free air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		UNIT		
STWIDGE	TANAMETER	MIN	NOM	MAX	ONT
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V
V _{IL}	Low-level input voltage			0.8	V
I _{lk}	Input clamp current			-18	mA
Гон	High-level output current			-3	mA
I _{OL}	Low-level output current			24	mA
T _{amb}	Operating free air temperature range	0		+70	°C

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DC ELECTRICAL CHARACTERISTICS(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST		LIMITS			UNIT
STWIBUL	PARAMETER		CONDITIONS ¹	MIN	TYP ²	MAX	UNIT	
.,	LP at least automorphism		V _{CC} = MIN, V _{IL} = MAX,	±10%V _{CC}	2.4			V
V _{OH}	High-level output voltage		V _{IH} = MIN, I _{OH} = MAX	±5%V _{CC}	2.7	3.4		V
V	Low level output voltage		$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}		0.35	0.50	V
V _{OL}	Low-level output voltage		$V_{IH} = MIN, I_{OL} = MAX$	±5%V _{CC}		0.35	0.50	V
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V	
I _I	Input current at maximum input voltage		$V_{CC} = MAX, V_I = 7.0V$			100	μΑ	
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$			20	μΑ	
I _{IL}	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
l _{OZH}	Off-state output current, high-level voltage ap	plied	$V_{CC} = MAX, V_O = 2.7V$				50	μΑ
l _{OZL}	Off-state output current, low-level voltage app	olied	$V_{CC} = MAX, V_O = 0.5V$				-50	μΑ
Ios	Short-circuit output current ³		V _{CC} = MAX		-60		-150	mA
l	Supply current (total)	74F373	V MAN			35	60	mA
Icc	Supply current (total)	74F374	V _{CC} = MAX			57	86	mA

NOTES:

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- 2. All typical values are at V_{CC} = 5V, T_{amb} = 25°C.

AC ELECTRICAL CHARACTERISTICS

						LIN	IITS		
SYMBOL	PARAMETER	TEST		_{mb} = +25 _{CC} = +5.0		$T_{amb} = 0^{\circ}C$ $V_{CC} = +5.$		UNIT	
OTHEOL	TANAMETER		CONDITION		pF, R _L :			$R_L = 500\Omega$	0.4
				MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay Dn to Qn		Waveform 3	3.0 2.0	5.3 3.7	7.0 5.0	3.0 2.0	8.0 6.0	ns
t _{PLH} t _{PHL}	Propagation delay E to Qn	74F373	Waveform 2	5.0 3.0	9.0 4.0	11.5 7.0	5.0 3.0	12.0 8.0	ns
t _{PZH}	Output enable time to high or low level		Waveform 6 Waveform 7	2.0 2.0	5.0 5.6	11.0 7.5	2.0 2.0	11.5 8.5	ns
t _{PHZ}	Output disable time from high or low level		Waveform 6 Waveform 7	2.0 2.0	4.5 3.8	6.5 5.0	2.0 2.0	7.0 6.0	ns
f _{max}	Maximum clock frequency		Waveform 1	150	165		140		ns
t _{PLH} t _{PHL}	Propagation delay CP to Qn	74F374	Waveform 1	3.5 3.5	5.0 5.0	7.5 7.5	3.0 3.0	8.5 8.5	ns
t _{PZH}	Output enable time to high or low level		Waveform 6 Waveform 7	2.0 2.0	9.0 5.3	11.0 7.5	2.0 2.0	12.0 8.5	ns
t _{PHZ}	Output disable time from high or low level		Waveform 6 Waveform 7	2.0 2.0	5.3 4.3	6.0 5.5	2.0 2.0	7.0 6.5	ns

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^{3.} Not more than one output should be shorted at a time. For testing IOS, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Latch/flip-flop

74F373/74F374

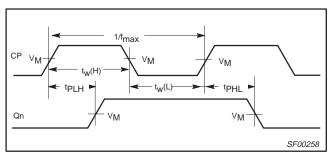
AC SETUP REQUIREMENTS

				LIMITS							
SYMBOL	SYMBOL PARAMETER				TEST CONDITION	T_{amb} = +25°C V_{CC} = +5.0V C_L = 50pF, R_L = 500 Ω			$T_{amb} = 0^{\circ}C \text{ to } +70^{\circ}C$ $V_{CC} = +5.0V \pm 10\%$ $C_{L} = 50pF, R_{L} = 500\Omega$		UNIT
				MIN	TYP	MAX	MIN	MAX			
t _{su} (H) t _{su} (L)	Setup time, high or low level Dn to E		Waveform 4	0 1.0			0 1.0		ns		
t _h (H) t _h (L)	Hold time, high or low level Dn to E	74F373	Waveform 4	3.0 3.0			3.0 3.0		ns		
t _w (H)	E Pulse width, high		Waveform 1	3.5			4.0		ns		
t _{su} (H) t _{su} (L)	Setup time, high or low level Dn to CP		Waveform 5	2.0 2.0			2.0 2.0		ns		
t _h (H) t _h (L)	Hold time, high or low level Dn to CP	74F374	Waveform 5	0 0			0 0		ns		
t _w (H) t _w (L)	CP Pulse width, high or low		Waveform 5	3.5 4.0			3.5 4.0		ns		

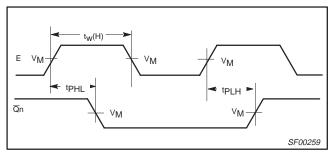
AC WAVEFORMS

For all waveforms, $V_M = 1.5V$.

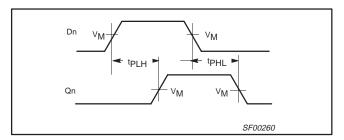
The shaded areas indicate when the input is permitted to change for predictable output performance.



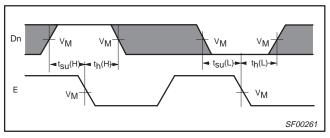
Waveform 1. Propagation delay for clock input to output, clock pulse widths, and maximum clock frequency



Waveform 2. Propagation delay for enable to output and enable pulse width



Waveform 3. Propagation delay for data to output



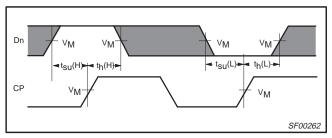
Waveform 4. Data setup time and hold times

Latch/flip-flop 74F373/74F374

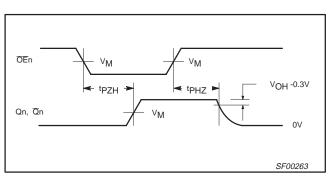
AC WAVEFORMS (Continued)

For all waveforms, $V_M = 1.5V$.

The shaded areas indicate when the input is permitted to change for predictable output performance.



Waveform 5. Data setup time and hold times

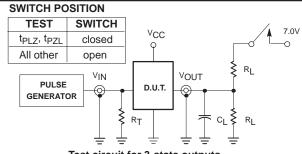


Waveform 6. 3-State output enable time to high level and output disable time from high level

Qn, Qn VM VM VpLz Vol. +0.3V

Waveform 7. 3-State output enable time to low level and output disable time from low level

TEST CIRCUIT AND WAVEFORMS

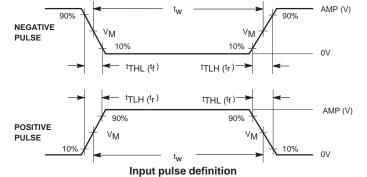


Test circuit for 3-state outputs

DEFINITIONS:

R_L = Load resistor; see AC electrical characteristics for value.

 $R_{T\,=\,}$ Termination resistance should be equal to Z_{OUT} of pulse generators.



family	INPUT PULSE REQUIREMENTS									
	amplitude	V_{M}	rep. rate	t _w	t _{TLH}	t _{THL}				
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns				

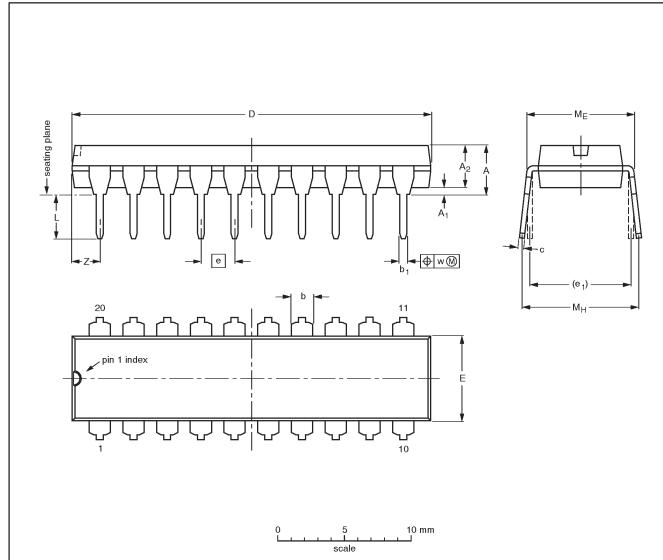
SF00265

Latch/flip-flop

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DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT146-1			SC603			92-11-17 95-05-24

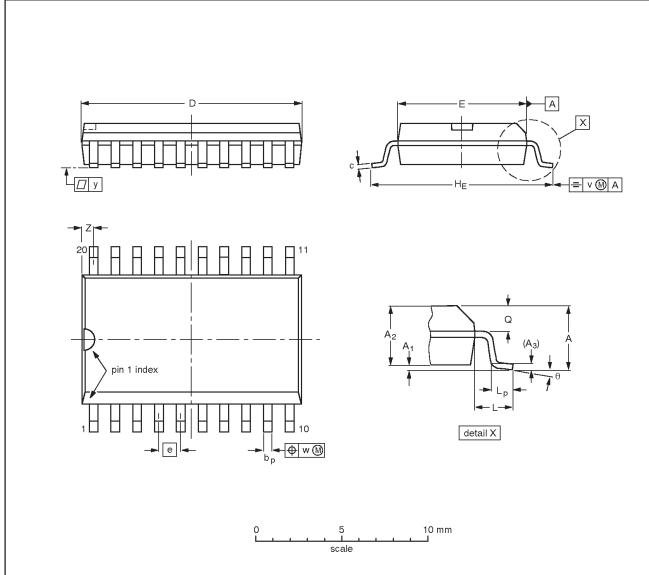
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Latch/flip-flop

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT163-1	075E04	MS-013AC				-95-01-24 97-05-22

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NOTES

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Latch/flip-flop

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DEFINITIONS							
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.					
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.					
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.					

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